



*A Leading Provider of Microcontrollers & Analog Semiconductors*

**Date:** 22 Jun 2011

**Product Category:** Memory

**Device Family:** 

**Notification subject:** CCB 1059: Qualification of 48L TSOP at PTI\_SZ Assembly Site.

**Notification text:** PCN Status:  
Initial notification

Microchip Parts Affected:  
See attachments of affected catalog part numbers (CPN) labeled as...  
PCN\_CYER-10JNWA553\_Affected\_CPN.xls  
PCN\_CYER-10JNWA553\_Affected\_CPN.pdf

Description of Change:  
Qualification of 48L TSOP package at PTI\_SZ assembly site.

Impacts to Data Sheet:  
None

Reason for Change:  
To Improve On-Time Delivery Performance

Change Implementation Status:  
In Progress

Estimated First Ship Date:  
October 5, 2011 (date code: 1141)

NOTE: Please be advised that during the transition period customers may receive pre and post change parts, due to existing inventory of the pre changed parts.

Markings to Distinguish Revised from Unrevised Devices:  
Traceability code

Revision History:  
June 22, 2011: Issued initial notification.

**Attachment(s):**

[PCN\\_CYER-10JNWA553\\_Affected\\_CPN.pdf](#) [PCN\\_CYER-10JNWA553\\_Affected\\_CPN.xls](#)  
[PCN\\_CYER-10JNWA553\\_Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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## Product Change Notification - CYER-10JNWA553

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PCN_CYER-10JNWA553
CATALOG_PART_NBR
SST38VF6401-90-4I-EKE
SST38VF6401-90-5C-EKE
SST38VF6401-90-5C-EKE-T
SST38VF6401-90-5I-EKE
SST38VF6402-90-5C-EKE
SST38VF6402-90-5I-EKE
SST38VF6403-90-5C-EKE
SST38VF6403-90-5I-EKE
SST38VF6404-90-5C-EKE
SST38VF6404-90-5I-EKE
SST39LF200A-45-4C-EKE
SST39LF200A-45-4C-EKE
SST39LF200A-45-4C-EKE-T
SST39LF200A-45-4C-EKE-T
SST39LF200A-55-4C-EKE
SST39LF200A-55-4C-EKE
SST39LF200A-55-4C-EKE-T
SST39LF200A-55-4C-EKE-T
SST39LF400A-55-4C-EKE
SST39LF400A-55-4C-EKE-T
SST39LF800A-55-4C-EKE
SST39LF800A-55-4C-EKE
SST39VF1601-70-4A-EKE
SST39VF1601-70-4A-EKE
SST39VF1601-70-4A-EKE-ZZ136
SST39VF1601-70-4A-EKE-ZZ136
SST39VF1601-70-4C-EKE
SST39VF1601-70-4C-EKE
SST39VF1601-70-4C-EKE-PP013
SST39VF1601-70-4C-EKE-PP013
SST39VF1601-70-4C-EKE-T
SST39VF1601-70-4C-EKE-T
SST39VF1601-70-4I-EKE
SST39VF1601-70-4I-EKE
SST39VF1601-70-4I-EKE-T
SST39VF1601-70-4I-EKE-T
SST39VF1601-70-4I-EKE-TZ009
SST39VF1601-70-4I-EKE-TZ009
SST39VF1601C-70-4C-EKE
SST39VF1601C-70-4I-EKE
SST39VF1601C-70-4I-EKE-TZ018
SST39VF1602-70-4A-EKE
SST39VF1602-70-4A-EKE
SST39VF1602-70-4A-EKE-ZZ136
SST39VF1602-70-4A-EKE-ZZ136
SST39VF1602-70-4C-EKE
SST39VF1602-70-4C-EKE
SST39VF1602-70-4C-EKE-T
SST39VF1602-70-4C-EKE-T
SST39VF1602-70-4I-EKE

SST39VF1602-70-4I-EKE
SST39VF1602-70-4I-EKE-T
SST39VF1602-70-4I-EKE-T
SST39VF1602C-70-4C-EKE
SST39VF1602C-70-4I-EKE
SST39VF1681-70-4C-EKE
SST39VF1681-70-4C-EKE
SST39VF1681-70-4C-EKE-T
SST39VF1681-70-4C-EKE-T
SST39VF1681-70-4I-EKE
SST39VF1681-70-4I-EKE
SST39VF1681-70-4I-EKE-T
SST39VF1681-70-4I-EKE-T
SST39VF1682-70-4C-EKE
SST39VF1682-70-4C-EKE
SST39VF1682-70-4C-EKE-T
SST39VF1682-70-4C-EKE-T
SST39VF1682-70-4I-EKE
SST39VF1682-70-4I-EKE
SST39VF200A-70-4C-EKE
SST39VF200A-70-4C-EKE
SST39VF200A-70-4C-EKE-T
SST39VF200A-70-4C-EKE-T
SST39VF200A-70-4I-EKE
SST39VF200A-70-4I-EKE
SST39VF200A-70-4I-EKE-T
SST39VF200A-70-4I-EKE-T
SST39VF3201-70-4C-EKE
SST39VF3201-70-4C-EKE
SST39VF3201-70-4C-EKE-T
SST39VF3201-70-4C-EKE-T
SST39VF3201-70-4I-EKE
SST39VF3201-70-4I-EKE
SST39VF3201-70-4I-EKE-T
SST39VF3201-70-4I-EKE-T
SST39VF3201B-70-4C-EKE
SST39VF3201B-70-4I-EKE
SST39VF3201B-70-4I-EKE-T
SST39VF3202-70-4C-EKE
SST39VF3202-70-4C-EKE
SST39VF3202-70-4I-EKE
SST39VF3202-70-4I-EKE
SST39VF3202B-70-4C-EKE
SST39VF3202B-70-4I-EKE
SST39VF400A-70-4C-EKE
SST39VF400A-70-4C-EKE-DD001
SST39VF400A-70-4C-EKE-DD001
SST39VF400A-70-4C-EKE-DD001-T
SST39VF400A-70-4C-EKE-DD001-T
SST39VF400A-70-4C-EKE-T
SST39VF400A-70-4I-EKE
SST39VF400A-70-4I-EKE-PP013

SST39VF400A-70-4I-EKE-PP013
SST39VF400A-70-4I-EKE-T
SST39VF6401B-70-4C-EKE
SST39VF6401B-70-4C-EKE
SST39VF6401B-70-4C-EKE-T
SST39VF6401B-70-4C-EKE-T
SST39VF6401B-70-4I-EKE
SST39VF6401B-70-4I-EKE
SST39VF6401B-70-4I-EKE-T
SST39VF6401B-70-4I-EKE-T
SST39VF6401B-70-4I-EKE-TZ009
SST39VF6401B-70-4I-EKE-TZ009
SST39VF6402B-70-4C-EKE
SST39VF6402B-70-4C-EKE
SST39VF6402B-70-4C-EKE-T
SST39VF6402B-70-4C-EKE-T
SST39VF6402B-70-4I-EKE
SST39VF6402B-70-4I-EKE
SST39VF800A-70-4A-EKE
SST39VF800A-70-4A-EKE
SST39VF800A-70-4C-EKE
SST39VF800A-70-4C-EKE
SST39VF800A-70-4C-EKE-T
SST39VF800A-70-4C-EKE-T
SST39VF800A-70-4I-EKE
SST39VF800A-70-4I-EKE
SST39VF800A-70-4I-EKE-T
SST39VF800A-70-4I-EKE-T
SST39VF800A-70-4I-EKE-TZ009
SST39VF800A-70-4I-EKE-TZ009

Parts Affected

SST38VF6401  
SST38VF6402  
SST38VF6403  
SST38VF6404  
SST39LF200A  
SST39LF400A  
SST39LF800A  
SST39VF1601  
SST39VF1601C  
SST39VF1602  
SST39VF1602C  
SST39VF1681  
SST39VF1682  
SST39VF200A  
SST39VF3201  
SST39VF3201B  
SST39VF3202  
SST39VF3202B  
SST39VF400A  
SST39VF6401B  
SST39VF6402B  
SST39VF800A



**MICROCHIP**

# **QUALIFICATION PLAN**

**PCN#: CYER-10JNWA553**

**Date:  
May 26, 2011**

**Qualification of 48L TSOP at PTI\_SZ Assembly Site**

Distribution

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Wichai K.  
Chaweng W.

Rangsun K.  
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**Purpose:** \_\_\_\_\_ Qualification of 48L TSOP at PTI\_SZ Assembly Site.

**Part No.:** \_\_\_\_\_ SST38VF6401 (SF8-120)

**BD No:** \_\_\_\_\_ SFMCX486MN401 Rev.00 (Engineering BD)

**CCB No:** \_\_\_\_\_ 1059

**Package:**

**Type** \_\_\_\_\_ 48L TSOP

**Width or Size** \_\_\_\_\_ 20 x 12 x 1.0 mm

**Die thickness:** \_\_\_\_\_ 11 mils

**Die size:** \_\_\_\_\_ 143 x 237 mils

**Lead frame:**

**Paddle size:** \_\_\_\_\_ 278.93x213.4 mils

**Material** \_\_\_\_\_ C7025

**Surface** \_\_\_\_\_ Copper with Ag ring plated on paddle

**Process** \_\_\_\_\_ Stamping

**Lead Lock** \_\_\_\_\_ Yes

**Part Number** \_\_\_\_\_ 048XCZ025/Fusheng

**Wire:**

**Material** \_\_\_\_\_ Au wire G5A (2N) /Nippon

**Die Attach Epoxy:**

**Part Number** \_\_\_\_\_ 4900GC/ Hitachi

**Conductive** \_\_\_\_\_ Yes

**Mold Compound:** \_\_\_\_\_ CEL-9241HF/ Hitachi

**Reliability Test plan:** \_\_\_\_\_ See attached, STD Package Reliability Test plan on each package.

Per FRM-39000CTG Revision G



Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Standard Pb-free Solderability	JESD22B-102E; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages. Mil. Std. 883-2011	22	5	1	27	> 95% lead coverage	5	Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.  30 bonds from a min. 5 devices.
Wire Bond Pull -WBP	Mil. Std. 883-2011	5	0	1	5	0	5	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5	30 bonds from a min. 5 devices.
Physical Dimensions	Measure per JESD22 B100 and B108	10	0	3	30	0	5	
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	+175 C for 504 hours or 150°C for 1008 hrs. Electrical test pre and post stress at +25C and hot temp.	45	5	1	50	0	10	For hot temp testing, pre/post test 1 lot at 85°C and 125°C (if applicable)
Preconditioning - Required for surface mount devices MSL-3 @ 260°C	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020C for package type; Electrical test pre and post stress at +25°C. Perform SAM analysis using the standard sample size.	231	15	3	738	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
HAST	+130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C and hot temp.	77	5	3	246	0	10	For hot temp testing, pre/post test 1 lot at 85°C and 125°C (if applicable).
UHAST	+130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs	77	5	3	246	0	10	
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP <sub>1</sub> on 5 devices from 1 lot; test following Temp Cycle stress.	77	5	3	246	0	15	For hot temp testing, pre/post test 1 lot at 85°C and 125°C (if applicable).